



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD60R950C6		<b>Issued</b>		17. October 2014	
<b>MA#</b>				MA001182966					
<b>Package</b>				PG-TO252-3-313		<b>Weight*</b>		318.08 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.144	0.67	0.67	6739	6739	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.25	46.31	462448	463050	
wire	non noble metal	aluminium	7429-90-5	0.516	0.16	0.16	1622	1622	
encapsulation	organic material	carbon black	1333-86-4	1.415	0.44		4449		
	plastics	epoxy resin	-	24.766	7.79		77862		
	inorganic material	silicondioxide	60676-86-0	115.341	36.26	44.49	362615	444926	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11758	11758	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4466	4477	
solder	noble metal	silver	7440-22-4	0.056	0.02		176		
	non noble metal	tin	7440-31-5	0.045	0.01		141		
	non noble metal	lead	7439-92-1	2.144	0.67	0.70	6742	7059	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60291	60369	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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